

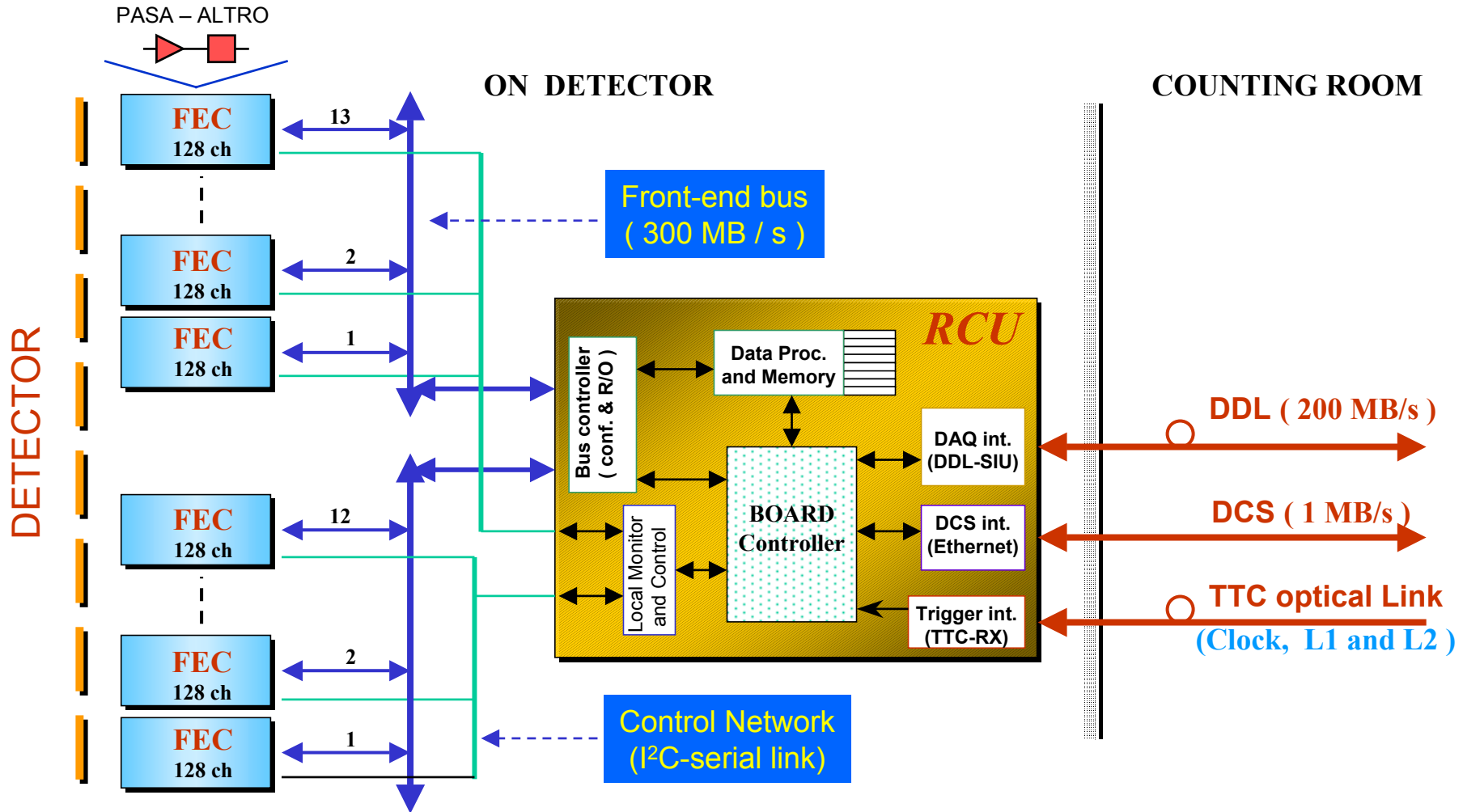
# Readout Electronics Radiation Tolerance in the Forward Region

CERN, 16 March 2004

Luciano Musa - CERN / PH - ED

# TPC FE AND READOUT ELECTRONICS

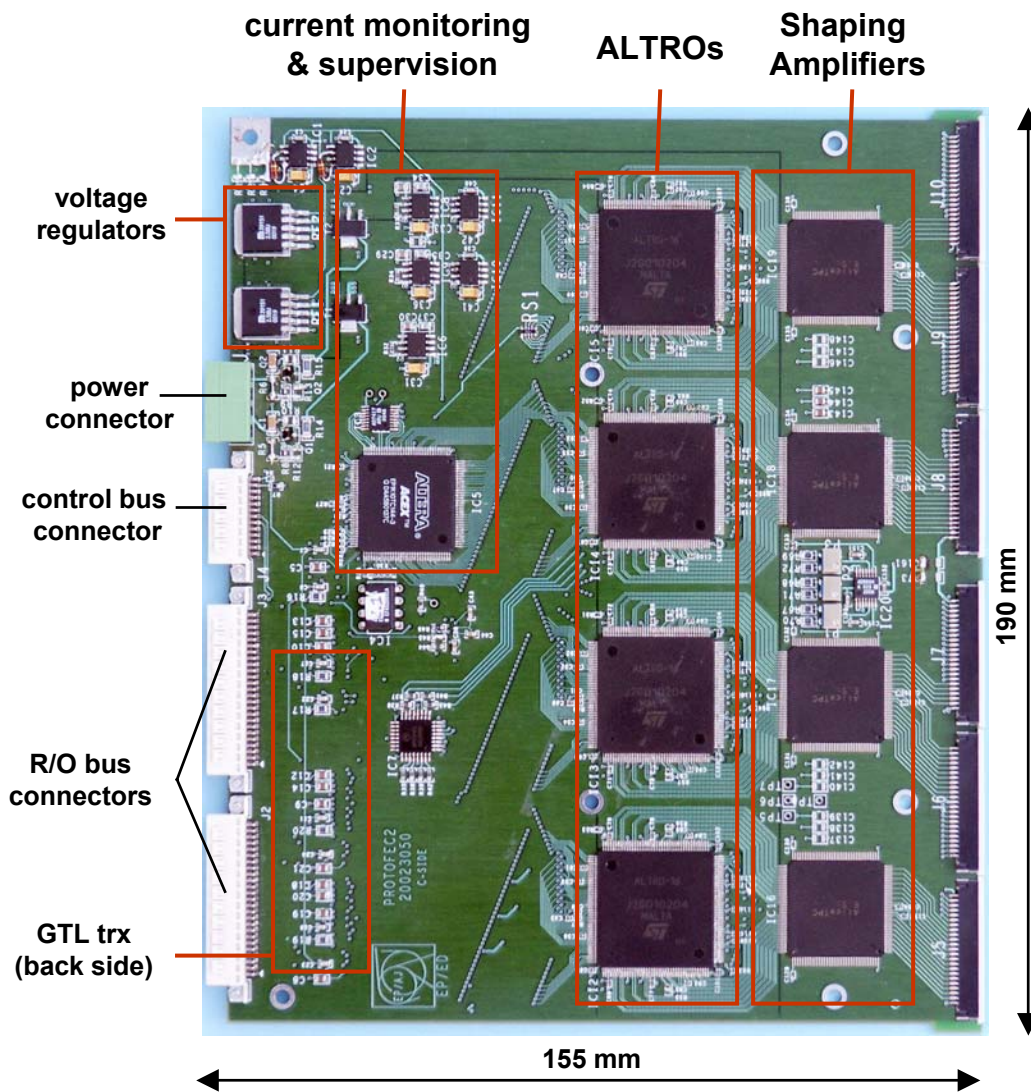
Each of the 36 TPC Sectors is served by 6 Readout Partitions



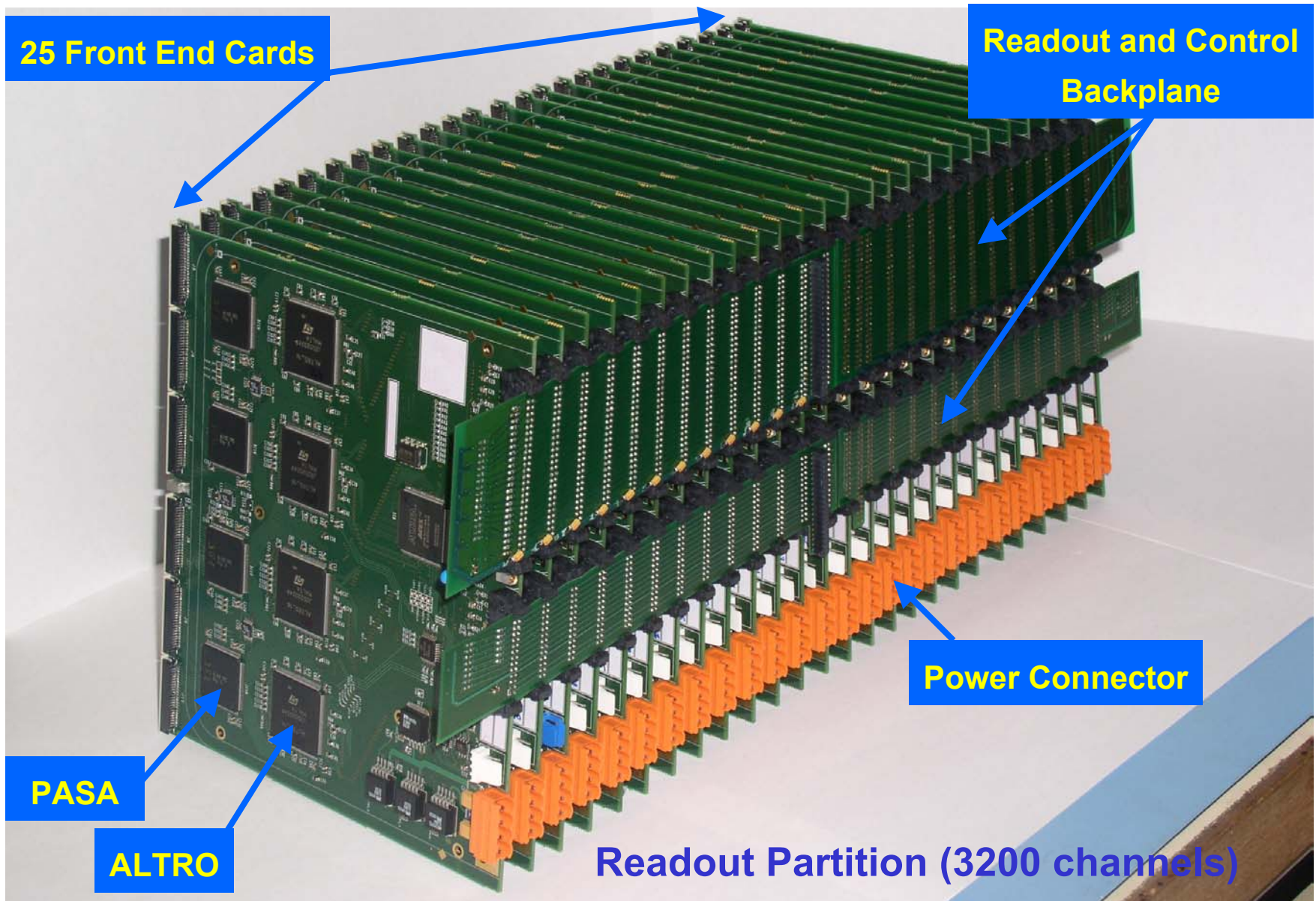
Overall TPC: 4356 Front End Card

216 Readout Partitions

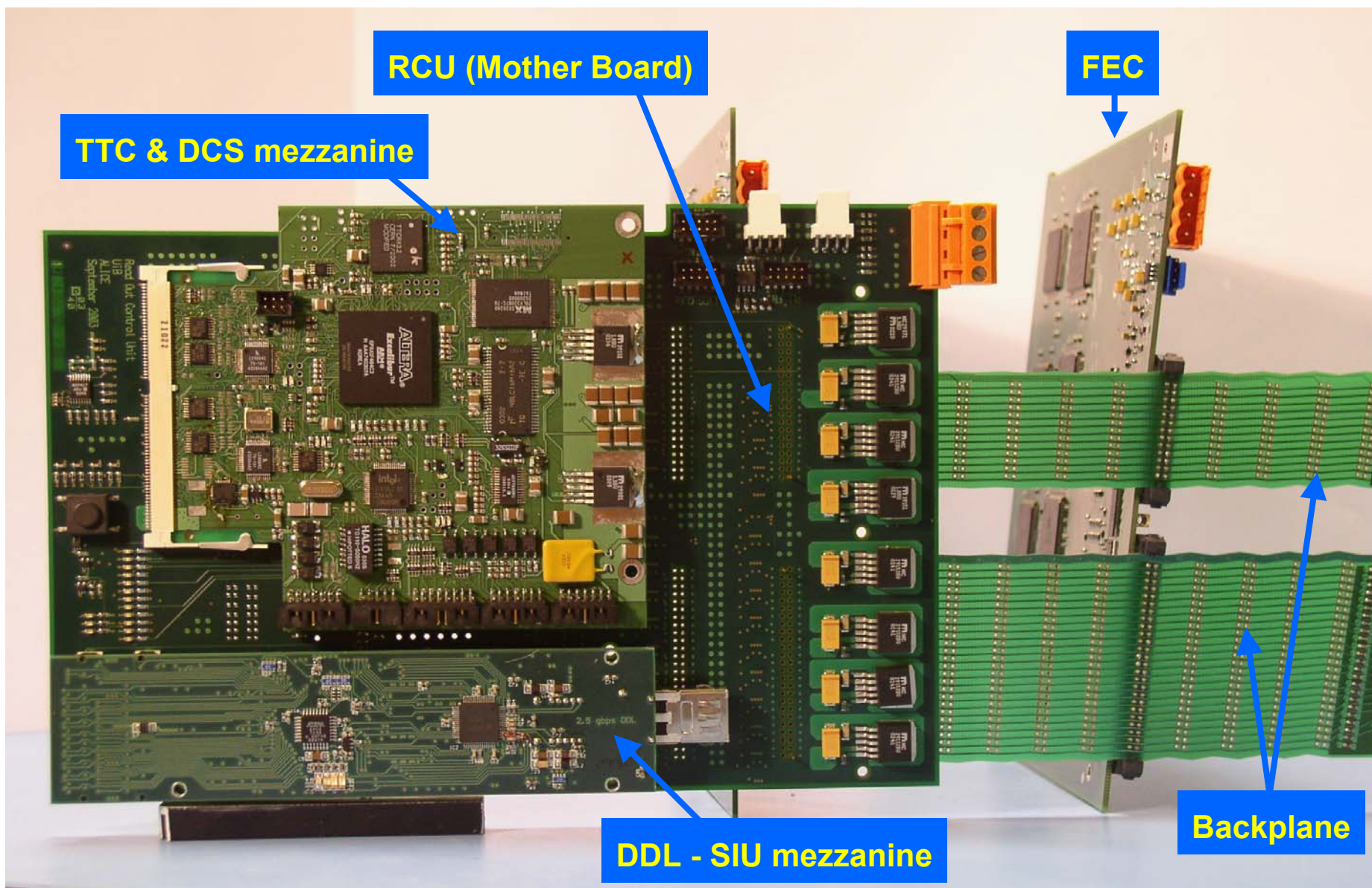
# TPC Front End Card



# TPC Readout Partition



# FEC – RCU Assembly

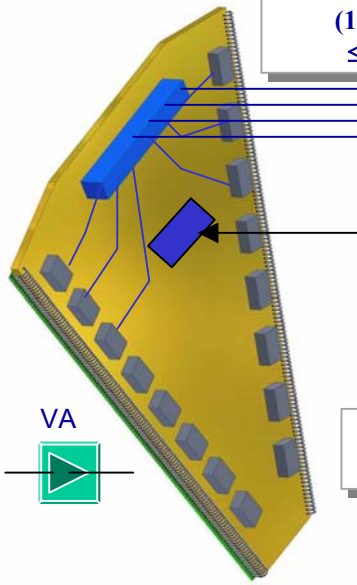


# FMD READOUT AND CONTROL ELECTRONICS

## ON DETECTOR

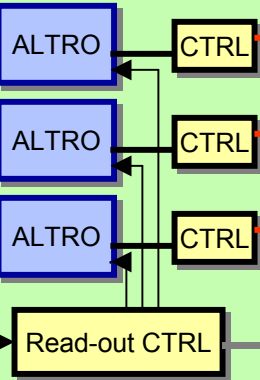
FMD Segment

Analog serial link  
(10 MHz)  
≤ 0.5 m



VA read-out control

FMD Digitizer

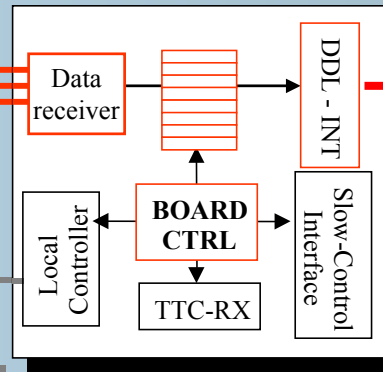


Digital serial links  
(15-20 m)

Trigger & Slow Ctrl

## IN CAVERN

FMD RCU



## IN COUNTING ROOM

Detector Data Link  
(50-60 m)

Slow control & Trigger

1 ring: 10/20 segments  
Full FMD: 70 segments

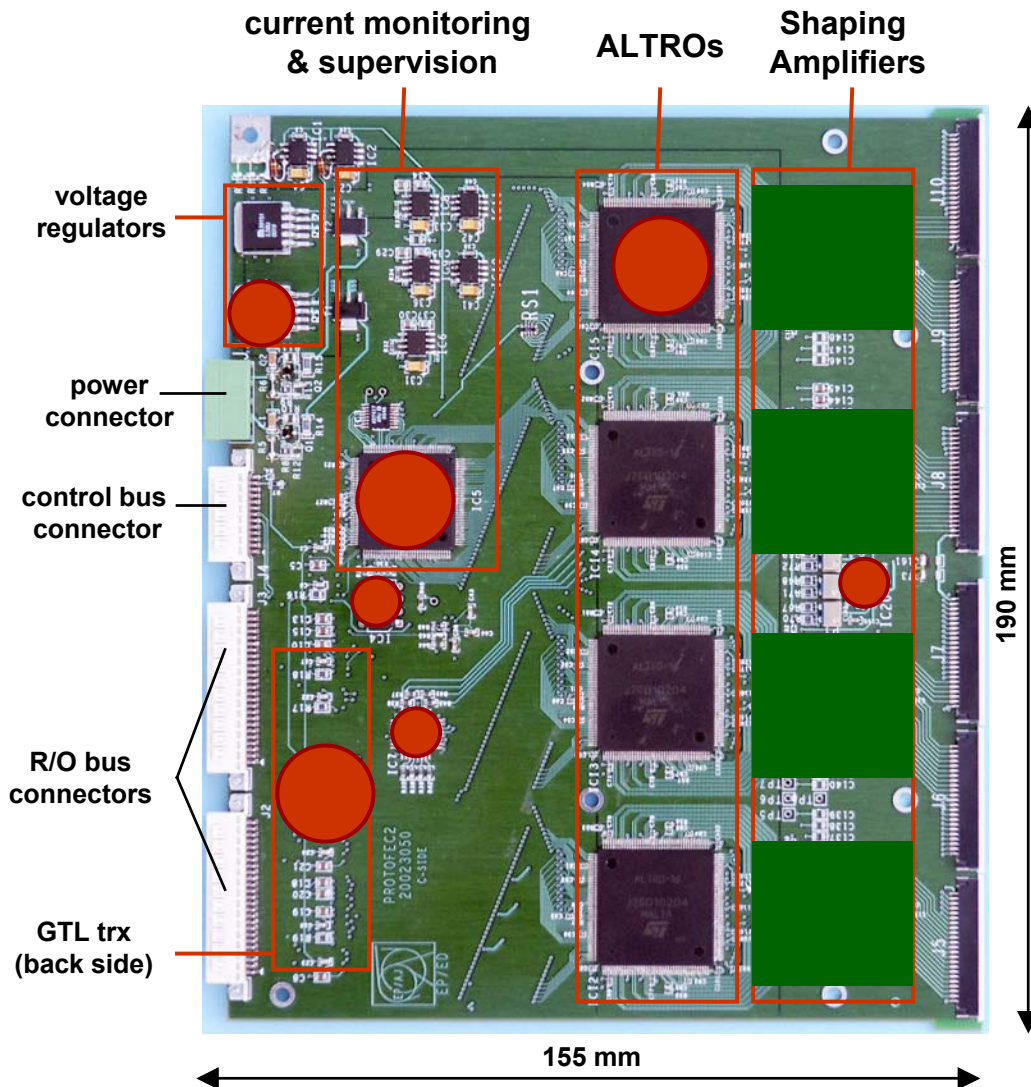
2 Digitizers  
10 Digitizers

1 RCU per side  
2 RCU's

1 DDL per side  
2 DDL's

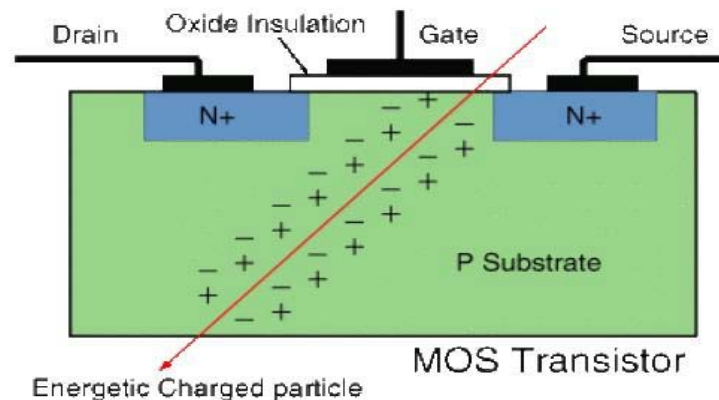
# FMD digitizer card based on the TPC FEC

## RADIATION SENSITIVE COMPONENTS



# Single Event Upset (SEU)

- High-energetic hadrons induce nuclear reactions in the silicon ( $E > 20 \text{ MeV}$  - protons, neutrons, pions, kaons)
- Intermediate energy neutrons ( $2 \text{ MeV} < E < 20 \text{ MeV}$ ) contribute little (10%) to SEUs
- (Almost) no effect due to thermal neutrons
- Heavy recoil ions from reactions ionise the material
- Protons do not deposit enough charge deposited by direct ionisation to cause a SEU
- Charge deposition leads to a change in state of a transistor (SEU)
- Soft error - can be corrected (rewriting or reprogramming)

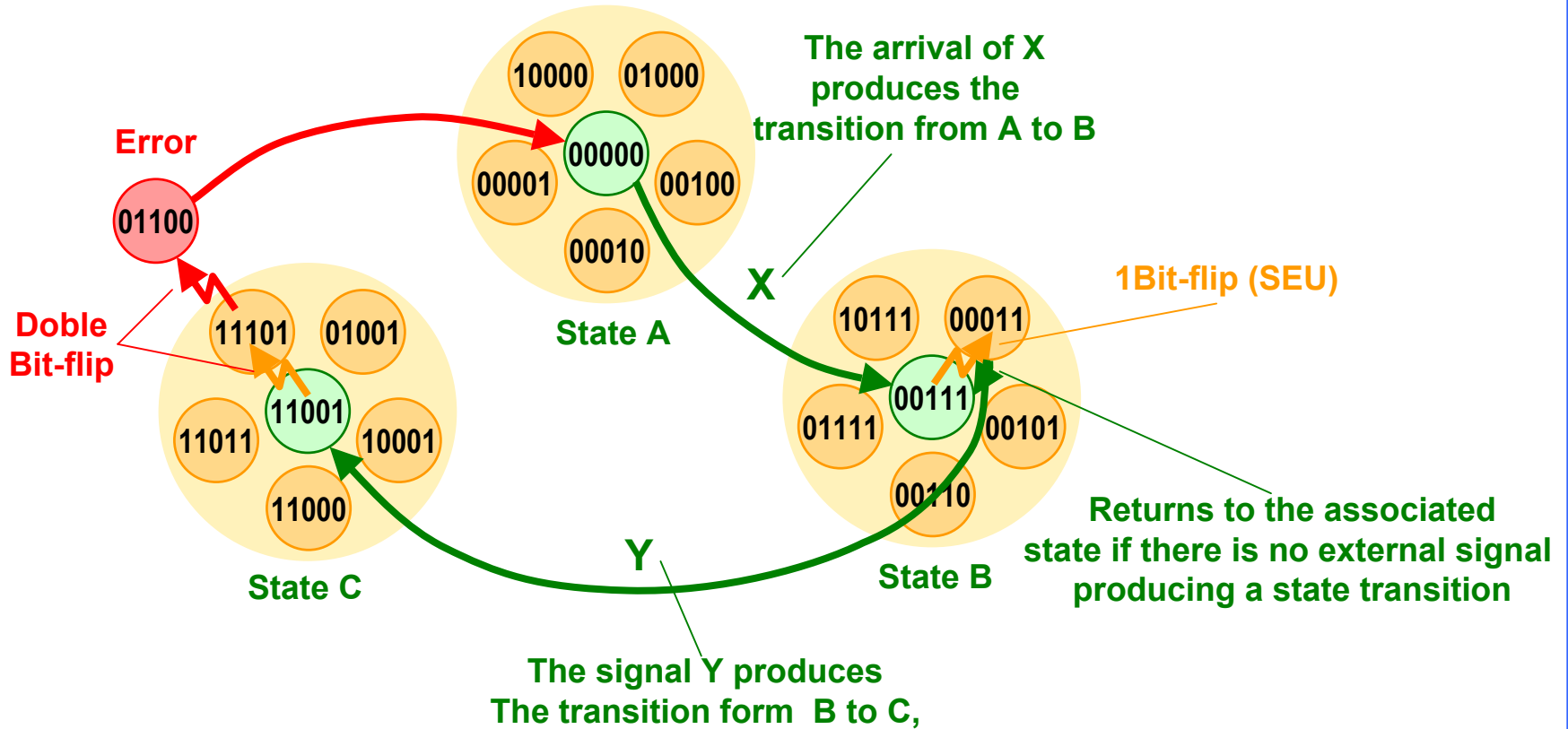




# SEU Protection

- Finite State Machine (FSM) protected by Hamming encoding

- Basic principle



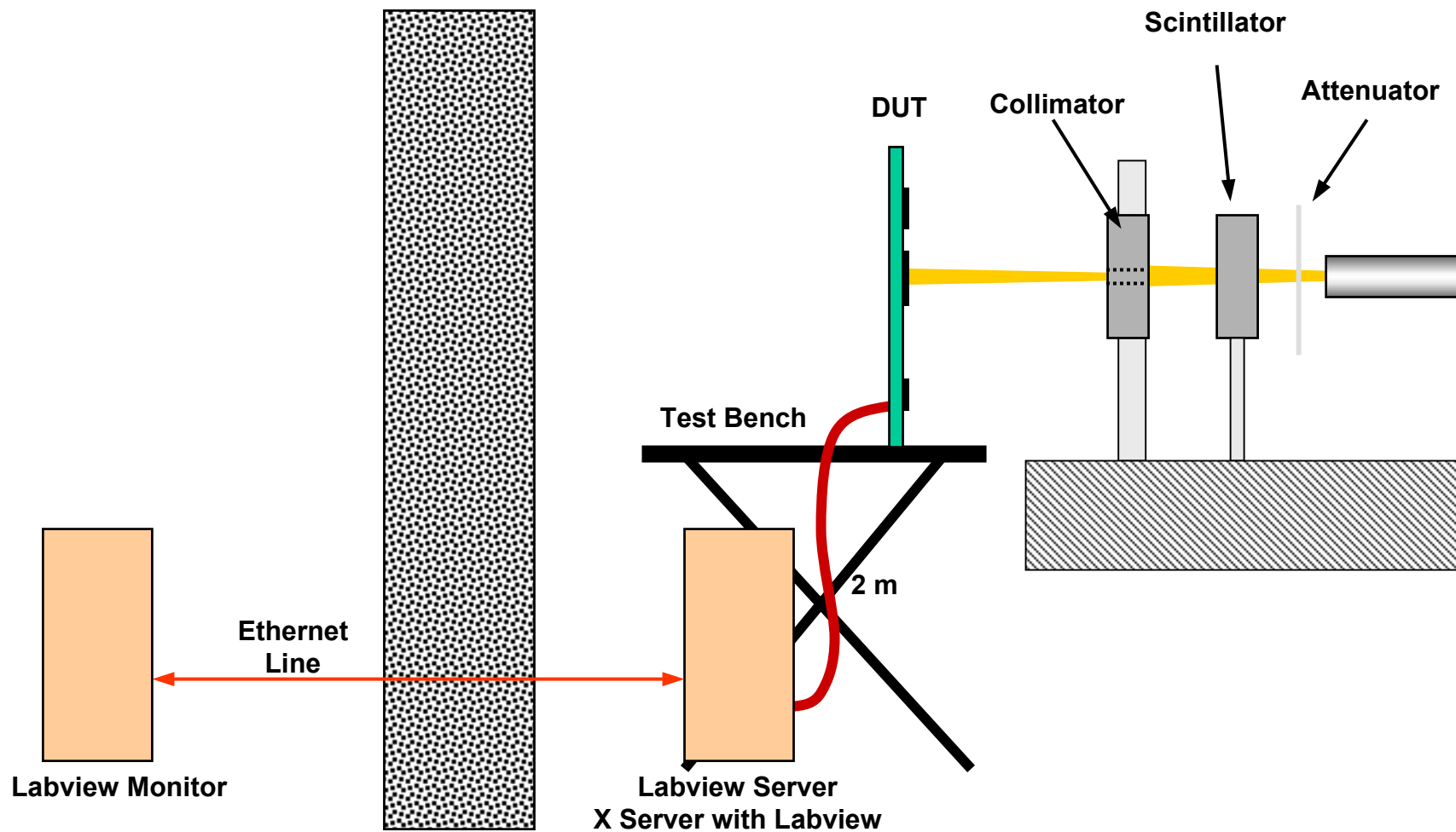
# Irradiation Facilities at UCL Cyclotron

Test at UCL, Louvain-la-Neuve, Belgium

Beam Type: 65 MeV protons

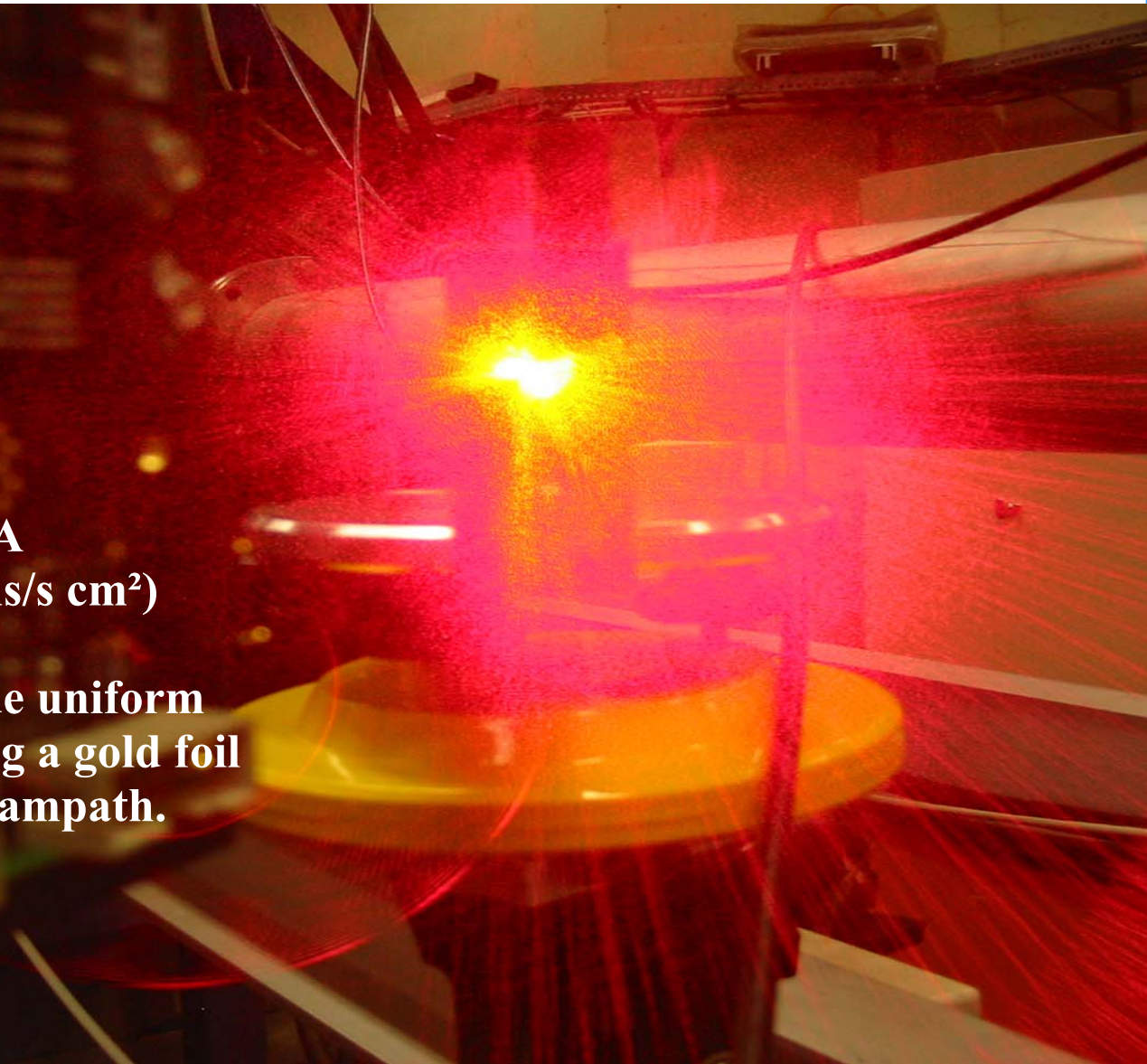
Proton Flux:  $1 \cdot 10^8$ ,  $5 \cdot 10^8$  p cm<sup>-2</sup> s<sup>-1</sup>

100 krad in 30 min at this flux



## Oslo Cyclotron

- 29 MeV external proton beam
- beamspot 1 x 1cm
- beam intensities  $> 10\text{pA}$   
(flux :  $0.6 \times 10^8$  protons/s  $\text{cm}^2$ )
- beam distribution made uniform by defocusing and using a gold foil placed upstream in beampath.



# FEC tested parts

Name	Type	No. Parts	Max. Dose (krad)	Test Method
ALTRO-16	CMOS	10	> 312	dynamic
MIC39151 (LDO) †	Bipolar	20	30	dynamic
MIC29371 (LDO) †	Bipolar	20	30	dynamic
GTL16612	Bi-CMOS	10	> 100	dynamic
MPC9109	CMOS	10	> 100	dynamic
OPA4364 †	Bipolar	10	> 30	dynamic
LM4040 †	Bipolar	10	> 30	dynamic
ACEX1K30	CMOS	10	> 100	dynamic
EPC1441	CMOS	8	> 10	powered
Electrolytic Cap	Tantalum	20	> 100	powered

† Part malfunction at mentioned dose

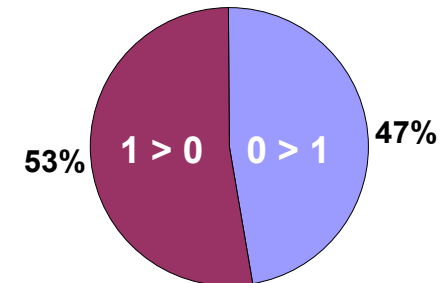
ALICE dose over 10 years is 3 krad

# ALTRO Radiation Test Results

## Error Cross Section

Memory Error Cross Section:  $1.10 \cdot 10^{-14}$   $\text{cm}^{-2} \text{bit}^{-1}$   
Register Error Cross Section:  $7.02 \cdot 10^{-14}$   $\text{cm}^{-2} \text{bit}^{-1}$   
Hamming Error Cross Section:  $9.50 \cdot 10^{-14}$   $\text{cm}^{-2} \text{bit}^{-1}$

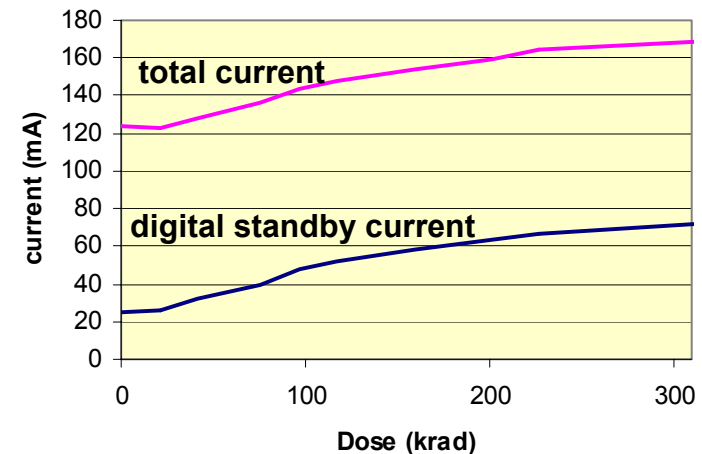
## bit-flip ratio



## Observations

- Slightly more flips from 1 to 0 than from 0 to 1
- **Digital current increases with dose (leakage increases)**
- Analog current stays the same
- ADC bit flips very rare
- Small spikes in analog part of ADC above 160 krad

## Digital current vs Dose



## Annealing

- After 2 weeks at room temperature: 43 mA standby current (+13.5% over total)
- After 3 months at room temperature: back to normal
- At a low flux, annealing and damage may compensate

**All 4 irradiated chips continue to work today**

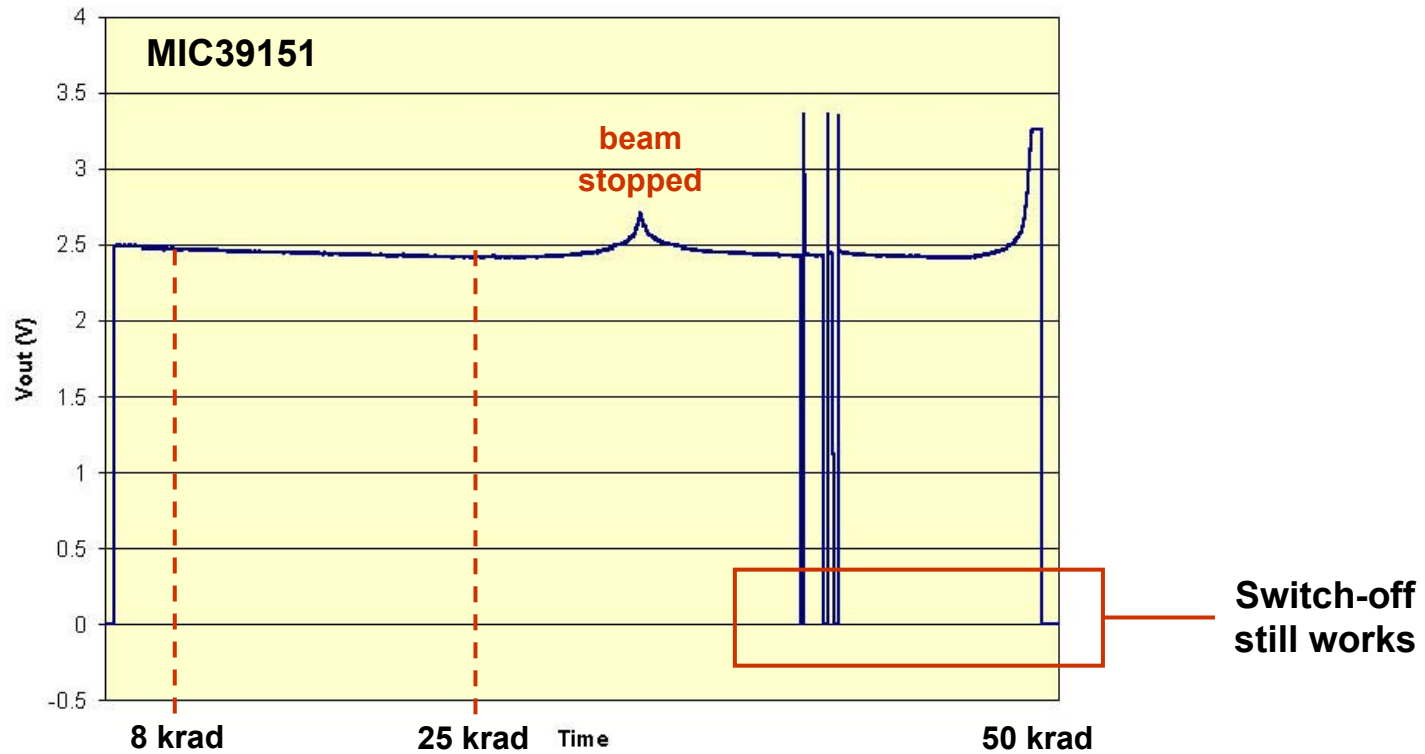
# System-level Consequences

For an FMD Digitizer Card equipped with 3 ALTROs

	Registers	Pedestal Memory	Data Memory	Hamming Machines
SEU per hour	$3.45 \cdot 10^{-5}$	$5.4 \cdot 10^{-4}$	$2.1 \cdot 10^{-3}$	$1.05 \cdot 10^{-4}$
MTBF	1200 days	77 days	20 days	397 days

# Regulator Test Results

MIC39151 died after 30 krad (switch-off still possible)



MIC39151 still usable for the TPC. Batch dispersion might be an issue



## Two types of concern

- Upsets in configuration SRAM cells
- Single bit-flips in register elements (can be avoided by design)

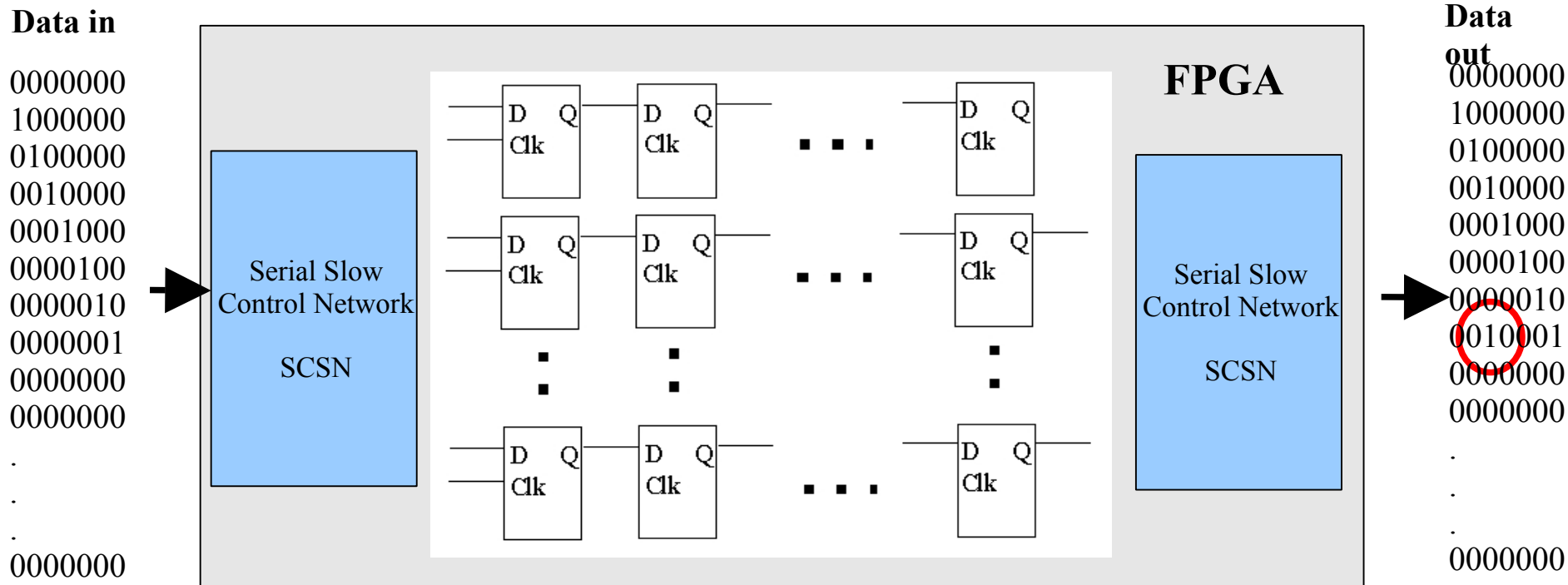
The APEX20K400E offers no direct readout of configuration SRAM

- Indirectly detection of configuration upset through the internal logic

Error observed reflects a change in logic due to a configuration upset, and not the configuration upset itself

# Upset detection in ALTERA FPGAs

A fixed pattern is shifted through and compared for setups when read out.



# Cross Section Results

Particle E > 10 MeV	Fluence [cm <sup>-2</sup> ] per 10 ALICE years (Simulation 1, non- absorber & absorber side)	Fluence [cm <sup>-2</sup> ] per 10 ALICE years (Simulation 2, incl. absorber side)
Protons	6 x 10 <sup>8</sup> 3 x 10 <sup>8</sup>	8.6 x 10 <sup>8</sup>
Pions, kaons	3.5 x 10 <sup>9</sup> 1.5 x 10 <sup>9</sup>	1.4 x 10 <sup>9</sup>
Neutrons (5%)	1.9 x 10 <sup>9</sup> 5 x 10 <sup>9</sup>	≈ 10 <sup>10</sup> ? tbc

Particle E > 10 MeV	Flux [sec <sup>-1</sup> cm <sup>-2</sup> ] (Simulation 1)	Flux [sec <sup>-1</sup> cm <sup>-2</sup> ] (Simulation 2)
Protons	24    13	34
Pions, kaons	140    60	56
Neutrons (5%)	76    206	450? tbc

# Error estimates per run

High Energetic Hadron Flux (@ TPCin): 250 - 550 hadrons / sec · cm<sup>2</sup>

	Error rate per run (4 hours) per device
FEC	$3 \cdot 10^{-4}$
RCU	$1.5 \cdot 10^{-2}$
DCS	$3 \cdot 10^{-2}$

# Conclusions (1)

## ➤ **ALTRO chip**

- TID > 300krad
- SEU: Control Logic is SEU free, Memories cross section too small to be a concern at the projected ALICE particle flux

## ➤ **FMD Digitizer (based on TPC FEC components)**

- TID ~ 30krad
- SEU (@ 500 hadrons / cm<sup>2</sup>·s)  
failure rate per run (4hours) per device ~ 3x10<sup>-4</sup>

## ➤ **FMD Digitizer (modified version based on CMOS LDOs and antifuse FPGA)**

- TID > 100 krad
- SEU free

# Conclusions (2)

## ➤ RCU (TPC actual version)

- TID  $\sim 30\text{krad}$
- SEU (@  $500\text{ hadrons / cm}^2\text{ s}$ )  
failure rate per run (4hours) per device  $\sim 5 \times 10^{-2}$